

| Absolute Maximum Ratings ($T_A = 25^{\circ}C$ unless otherwise noted) | | | | |
|---|----------------------------------|------------|-------|--|
| Parameter | Symbol | Maximum | Units | |
| Drain-Source Voltage | V _{DS} | 30 | V | |
| Gate-Source Voltage | V _{GS} | ±20 | V | |
| Drain Current (T _A =25°C) | | 8 | А | |
| Drain Current (T _A =75°C) | l _D | 4.5 | А | |
| Pulsed Drain Current ^a | I _{DM} | 40 | А | |
| Avalanche Energy (L= 0.1 mH) | E _{AS} | 25 | mJ | |
| Power Dissipation ^b (T _A =25°C) | | 2 | W | |
| Power Dissipation ^b (T _A =75°C) | PD | 1.2 | W | |
| Junction and Storage Temperature Range | T _{J,} T _{STG} | -55 ~ +150 | °C | |

| Thermal Characteristics | | | | |
|---|------------------|---------|-------|--|
| Parameter | Symbol | Maximum | Units | |
| Junction-to-Ambient ^a (t \leq 10s) | 5 | 42 | °C/W | |
| Junction-to-Ambient ^{a,d} (Steady-State) | R _{θJA} | 62 | °C/W | |
| Junction-to-Lead (Steady-State) | R _{ejL} | 4 | °C/W | |

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|----------------------|---------------------------------------|--|-----|------|------|-------|
| Off Char | acteristics | | · | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | V_{GS} = 0V , I _D = 250uA | 30 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V_{DS} = 30V , V_{GS} = 0V | | | 1 | uA |
| I _{GSS} | Gate-Body Leakage Current | V_{GS} = ±20V, V_{DS} = 0V | | | ±100 | nA |
| On Chara | acteristics | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | V_{DS} = V_{GS} , I_D = 250 uA | 1.0 | 1.8 | 2.5 | V |
| R _{DS(ON))} | Drain-Source On-State Resistance | V_{GS} = 10V , I_D = 10A | | 11 | 15 | mΩ |
| | | V_{GS} = 4.5V , I _D = 6A | | 15 | 20 | mΩ |
| g fs | Forward Transconductance | V_{DS} = 5.0V , I_D = 12A | | 35 | | S |
| Drain-So | ource Diode Characteristics | | | | | |
| V_{SD} | Diode Forward Voltage | $V_{GS} = 0V$, $I_S = 1.0A$ | | | 1.1 | V |
| Is | Maximum Body-Diode Continuous Current | | | | 40 | Α |
| Dynamic | Characteristics | | | | | |
| Ciss | Input Capacitance | | | 940 | | pF |
| C _{oss} | Output Capacitance | V _{DS} = 15V , V _{GS} = 0V f = 1.0MHz | | 132 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 111 | | pF |
| Switchin | g Characteristics | | | | | |
| Qg | Total Gate Charge | | | 10.2 | | nC |
| Q_{gs} | Gate-Source Charge | V_{DS} = 15V , I_D = 15A V_{GS} = 4.5V | | 4.3 | | nC |
| \mathbf{Q}_{gd} | Gate-Drain Charge | | | 3.5 | | nC |
| t _{D(ON}) | Turn-On Delay Time | V _{DD} = 15V , ID = 15A V _{GS} = 10 V R _{GEN} = 3.3 ohm | | 5 | | ns |
| tr | Turn-On Rise Time | | | 8 | | ns |
| $t_{D(OFF)}$ | Turn-Off Delay Time | | | 32 | | ns |
| t _f | Turn-Off Fall Time | | | 4 | | ns |

a. Repetitive rating, Pulse width limited by junction temperature T_{J(MAX)}=150 °C. Ratings are based on low frequency and duty cycles to keep initial T_J=25 °C

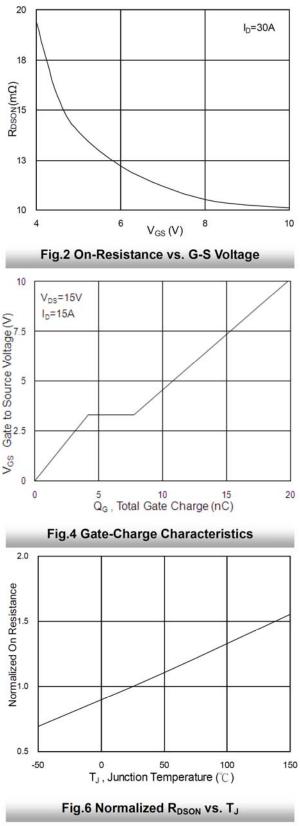
b. The power dissipation P_D is based on $T_{J(MAX)}$ =150 °C , using \leqslant 10s junction-to-ambient thermal resistance.

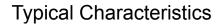
c. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}$ C. The value in any given application depends on the user's specific board design.

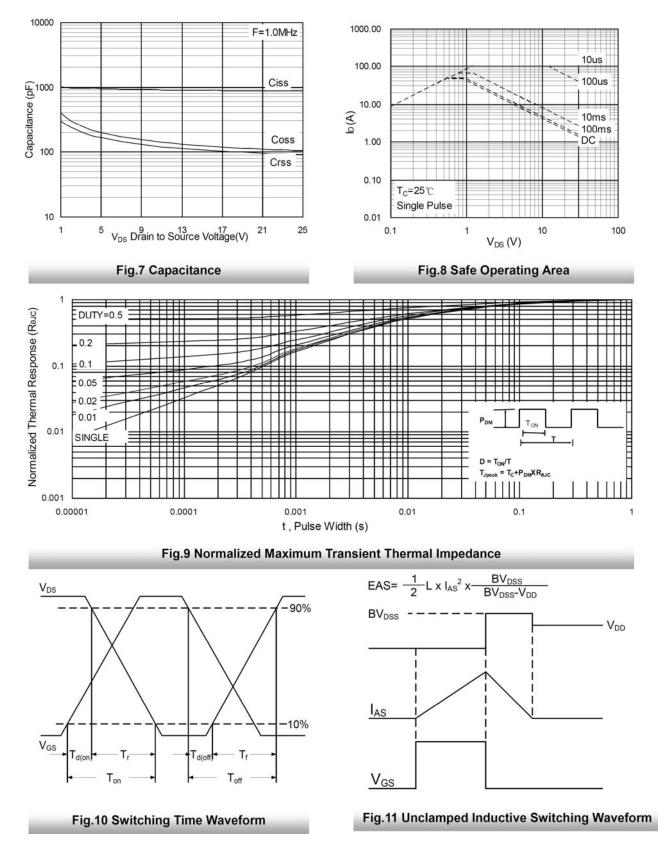
d. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

Typical Characteristics 120 20 V_{GS}=10V 100 V_{GS}=7V b Drain Current (A) 18 V_{GS}=5V 80 Rpson(mΩ) V_{GS}=4.5V 60 40 V_{GS}=3V 13 20 0 10 $^{0.5}\mathrm{V}_{\mathrm{DS}}$, Drain-to-Source Voltage (V) 0 3 4 Fig.1 Typical Output Characteristics 12 10 I_=15A 10 Gate to Source Voltage (V) ls Source Current(A) 8 6 T**J=150°**℃ T_=25 4 2 V_{GS} 0 0 V_{SD}, Source-to-Drain Voltage (V) 0 0 1.2 Fig.3 Forward Characteristics of Reverse 2.0 1.5 Normalized On Resistance Normalized VGS(th) 0.5 0 -50 T_{J}^{0} ,Junction Temperature (${}^{100}_{C}$) -50 150 Fig.5 Normalized V_{GS(th)} vs. T_J

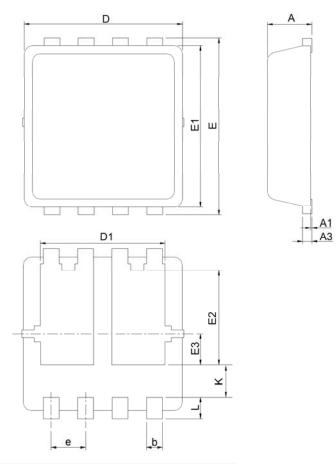
Typical Characteristics







DFN3x3EP-8L Package



| SYMBOL | DFN3x3-8 | | | |
|--------|-------------|-------|--------|-------|
| | MILLIMETERS | | INCHES | |
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.80 | 1.00 | 0.031 | 0.039 |
| A1 | 0.00 | 0.05 | 0.000 | 0.002 |
| A3 | 0.10 | 0.25 | 0.004 | 0.010 |
| b | 0.24 | 0.35 | 0.009 | 0.014 |
| D | 2.90 | 3.10 | 0.114 | 0.122 |
| D1 | 2.25 | 2.45 | 0.089 | 0.096 |
| E | 3.10 | 3.30 | 0.122 | 0.130 |
| E1 | 2.90 | 3.10 | 0.114 | 0.122 |
| E2 | 1.65 | 1.85 | 0.065 | 0.073 |
| E3 | 0.56 | 0.58 | 0.022 | 0.023 |
| е | 0.65 BSC | | 0.026 | BSC |
| к | 0.475 | 0.775 | 0.019 | 0.031 |
| L | 0.30 | 0.50 | 0.012 | 0.020 |

RECOMMENDED LAND PATTERN

